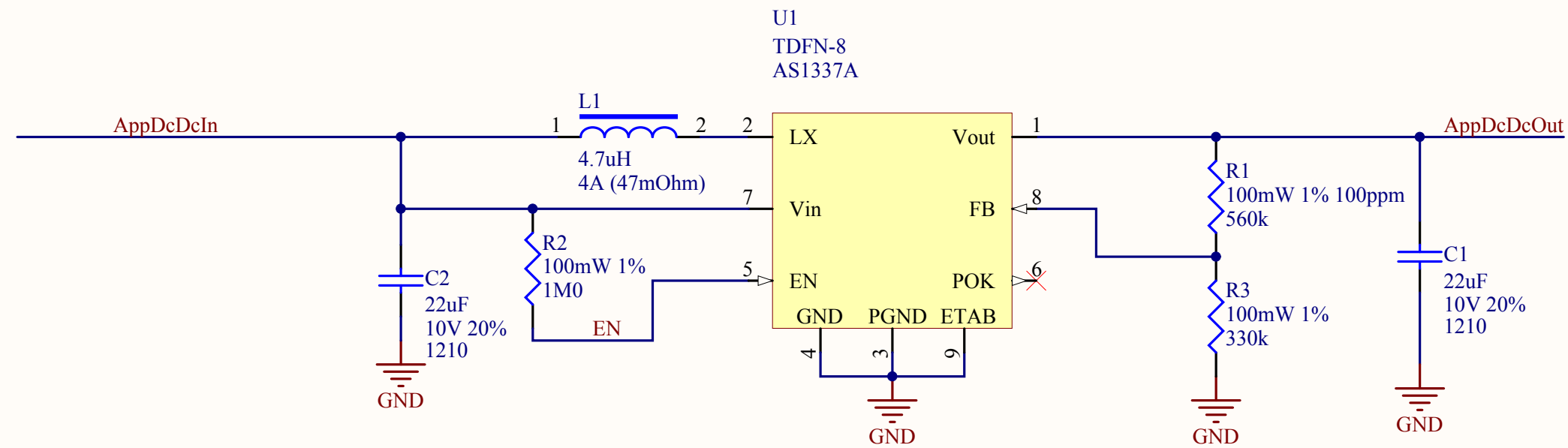


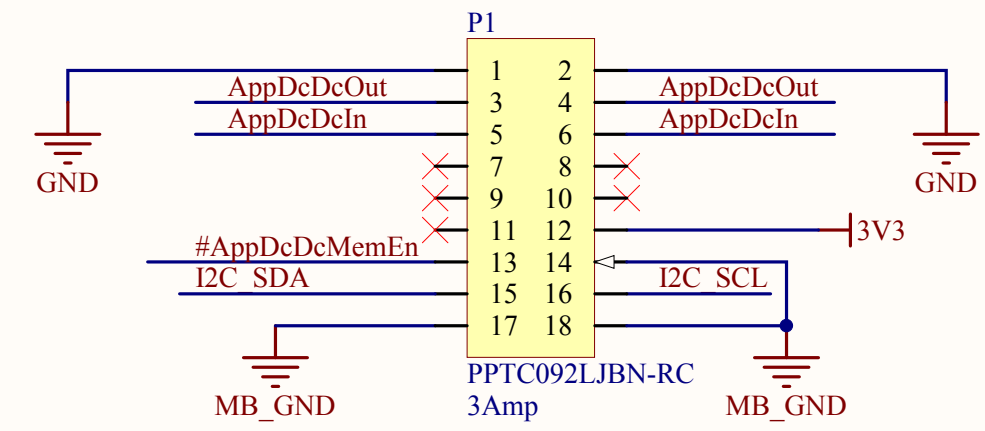
DC/DC convertor



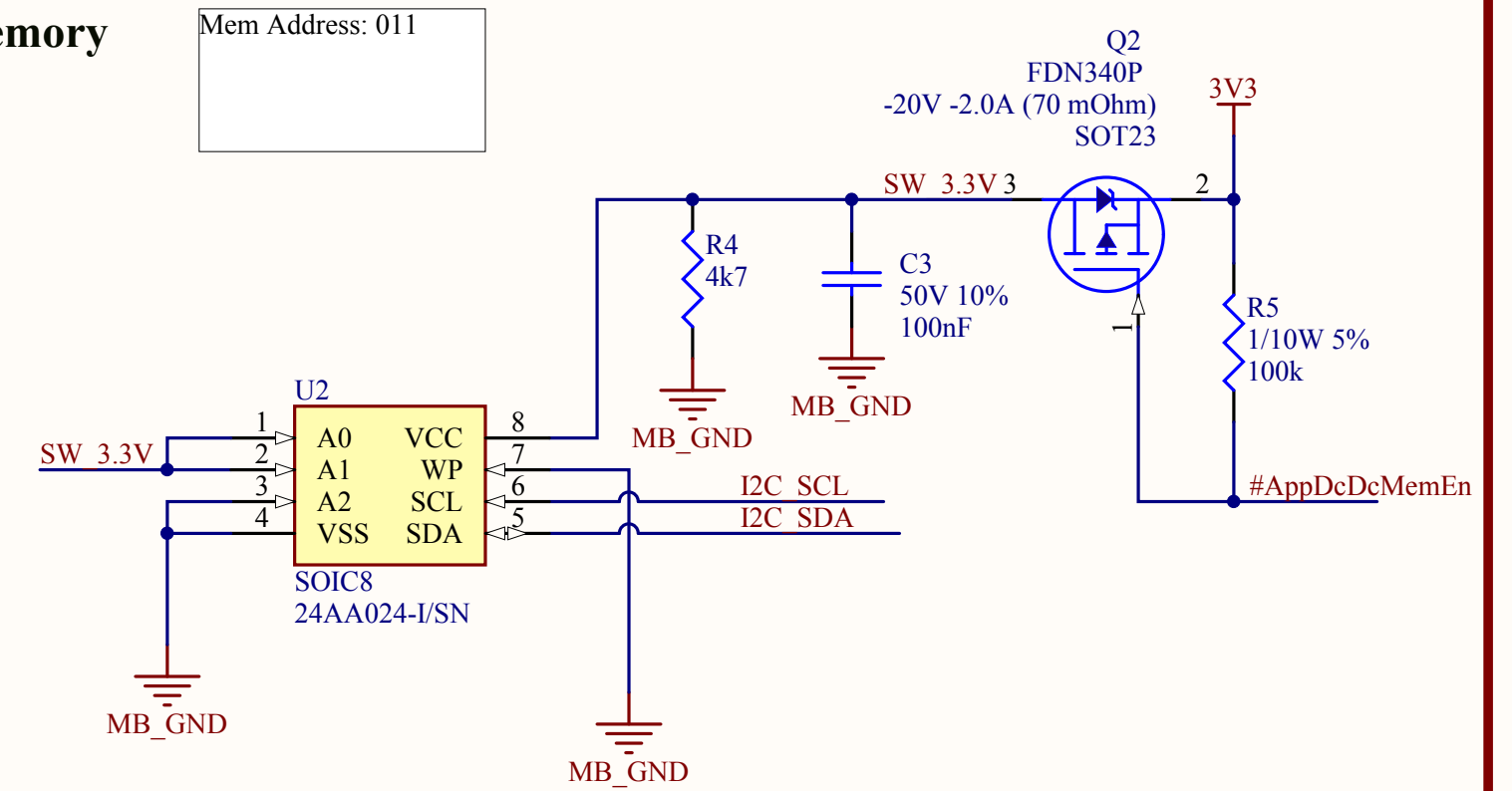
Vin = 0.65 to 4.55V (5V Tolerant)
 Vout = 3.3V
 Iout = 200mA
 Switching frequency = 1.2Mhz
 Start-Up voltage=0.85V

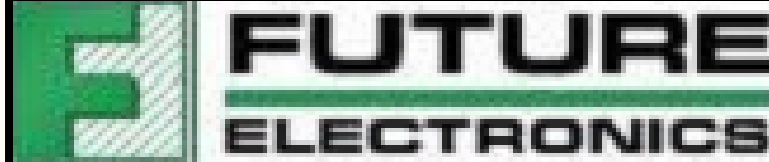
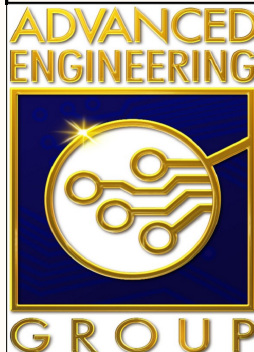
0603 footprints not shown

Connector



Block Memory



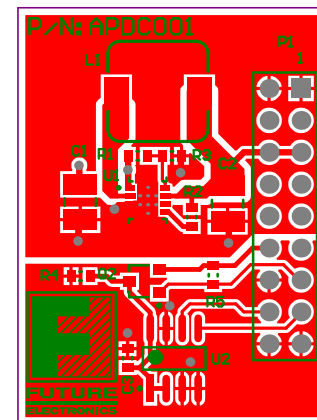
	Future Electronics - Advanced Engineering Group 237 Hymus Blvd. Pointe-Claire, Quebec, Canada H9R 5C7			
	Project Name APDC_001_R01.PrjPCB			
	Designed by N.Gautam		Title Application DC/DC- 3.3V/200mA	
	Drawn by N.Gautam			
Checked by H. Letourneau		Size B	Dwg No. FEN-2858-APDC001-SCH-R1	Rev 1.0
Approved by H. Letourneau		Date 2012-02-15	Sheet 1 of 1	

Layers

Top Layer	Multi-Layer
Mechanical 16	Top Overlay
	Keep-Out Layer

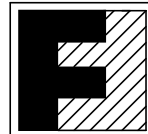
NOTES: < UNLESS OTHERWISE SPECIFIED >

- 1. BOARD SPECS - BOARD SHALL BE MANUFACTURED TO MEET ALL SPECS DEFINED UNDER IPC-A-600.
- 2. BASE MATERIAL - FR4 62mils, COPPER 1/1 OZ./SQ.FT.
- 3. PLATING - COPPER 1.0 OZ./SQ.FT.
- 4. FINISH - LEAD FREE HASL
- 5. GERBER FILES - SUPPLIED GERBER FILES MUST NOT BE MODIFIED BY MANUFACTURER WITHOUT PRIOR PERMISSION FROM THE CLIENT.
- 6. DRILLING - ALL HOLES TO BE DRILLED CONCENTRIC TO THEIR CIRCULAR BASE TO WITHIN .01 RADIUS.
- 7. REGISTRATION - REGISTRATION OF PATTERNS TO BE WITHIN .01 LOCATION OF PATTERN ON BOARD TO
- 8. TOOLING HOLES - NO HOLES SHALL BE PERMITTED WITHIN THE BOARD AREA, EXCEPT THOSE INDICATED IN THE DRILL LEGEND.
- 9. PLATED HOLES - HOLES TO BE PLATED-THROUGH TO A FINISHED DIAMETER AS SHOWN IN DRILL LEGEND, MINIMUM THICKNESS .0014 UNLESS OTHERWISE SPECIFIED.
- 10. SOLDER MASK - APPLY GREEN SOLDER MASK AS PER SPECIFIED IPC-SM-840 TO BOTH SIDES OF PCB OVER BARE COPPER
- 11. SILKSCREEN - APPLY ON COMPONENT TOPSIDE OF PCB IN WHITE EPOXY BASED INK.



- CONFIDENTIAL -

THIS DRAWING CONTAINS PROPRIETARY INFORMATION WHICH MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE WHATSOEVER OR USED FOR MANUFACTURING PURPOSES WITHOUT PRIOR WRITTEN PERMISSION FROM THE FUTURE ELECTRONICS CORPORATION.

 FUTURE ELECTRONICS	Future Electronics – Advanced Engineering Group 237 Hymus Blvd Pointe-Claire, Quebec, Canada H9R 5C7		
	Designed by: Navin Gautam	Project # PRJ-2858 – eHarvesting	
Drawn by: Navin Gautam	Title: Application DcDc 001		
Checked by: Hugo Letourneau	Size: A	DWG NO: FEN-2858-APDC001-PCB-R1	REV: 1
Approved by: Hugo Letourneau	Date: Jan 2 2012	Sheet 1 of 1	

Layers

Multi-Layer

Bottom Layer

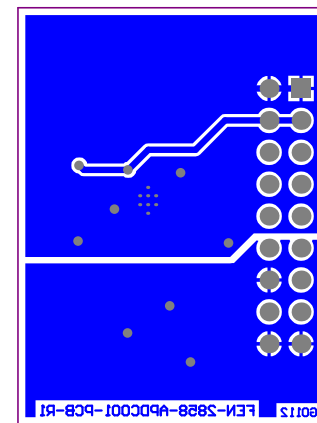
Mechanical 16

Bottom Overlay

Keep-Out Layer

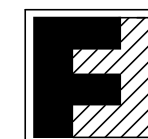
NOTES: < UNLESS OTHERWISE SPECIFIED >

- 1. BOARD SPECS - BOARD SHALL BE MANUFACTURED TO MEET ALL SPECS DEFINED UNDER IPC-A-600.
- 2. BASE MATERIAL - FR4 62mils, COPPER 1/1 OZ./SQ.FT.
- 3. PLATING - COPPER 1.0 OZ./SQ.FT.
- 4. FINISH - LEAD FREE HASL
- 5. GERBER FILES - SUPPLIED GERBER FILES MUST NOT BE MODIFIED BY MANUFACTURER WITHOUT PRIOR PERMISSION FROM THE CLIENT.
- 6. DRILLING - ALL HOLES TO BE DRILLED CONCENTRIC TO THEIR CIRCULAR BASE TO WITHIN .01 RADIUS.
- 7. REGISTRATION - REGISTRATION OF PATTERNS TO BE WITHIN .01 LOCATION OF PATTERN ON BOARD TO
- 8. TOOLING HOLES - NO HOLES SHALL BE PERMITTED WITHIN THE BOARD AREA, EXCEPT THOSE INDICATED IN THE DRILL LEGEND.
- 9. PLATED HOLES - HOLES TO BE PLATED-THROUGH TO A FINISHED DIAMETER AS SHOWN IN DRILL LEGEND, MINIMUM THICKNESS .0014 UNLESS OTHERWISE SPECIFIED.
- 10. SOLDER MASK - APPLY GREEN SOLDER MASK AS PER SPECIFIED IPC-SM-840 TO BOTH SIDES OF PCB OVER BARE COPPER
- 11. SILKSCREEN - APPLY ON COMPONENT TOPSIDE OF PCB IN WHITE EPOXY BASED INK.



- CONFIDENTIAL -

THIS DRAWING CONTAINS PROPRIETARY INFORMATION WHICH MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE WHATSOEVER OR USED FOR MANUFACTURING PURPOSES WITHOUT PRIOR WRITTEN PERMISSION FROM THE FUTURE ELECTRONICS CORPORATION.



**FUTURE
ELECTRONICS**

Future Electronics – Advanced Engineering Group
237 Hymus Blvd
Pointe-Claire, Quebec, Canada
H9R 5C7

ADVANCED
ENGINEERING

Designed by:
Navin Gautam

Drawn by:
Navin Gautam

Checked by:
Hugo Letourneau

Approved by:
Hugo Letourneau

Project # PRJ-2858 – eHarvesting

Title: Application DcDc 001

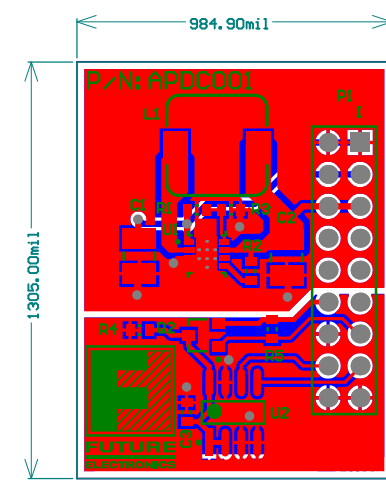
Size: A	DWG NO: FEN-2858-APDC001-PCB-R1	REV: 1
---------	---------------------------------	--------

Date: Jan 2 2012	Sheet 1 of 1
------------------	--------------


Layers	
Top Layer	Multi-Layer
Bottom Layer	
Mechanical 16	Top Overlay
Bottom Overlay	Keep-Out Layer

NOTES: < UNLESS OTHERWISE SPECIFIED >

- BOARD SPECS - BOARD SHALL BE MANUFACTURED TO MEET ALL SPECS DEFINED UNDER IPC-A-600.
- BASE MATERIAL - FR4 62mils, COPPER 1/1 OZ./SQ.FT.
- PLATING - COPPER 1.0 OZ./SQ.FT.
- FINISH - LEAD FREE HASL
- GERBER FILES - SUPPLIED GERBER FILES MUST NOT BE MODIFIED BY MANUFACTURER WITHOUT PRIOR PERMISSION FROM THE CLIENT.
- DRILLING - ALL HOLES TO BE DRILLED CONCENTRIC TO THEIR CIRCULAR BASE TO WITHIN .01 RADIUS.
- REGISTRATION - REGISTRATION OF PATTERNS TO BE WITHIN .01 LOCATION OF PATTERN ON BOARD TO
- TOOLING HOLES - NO HOLES SHALL BE PERMITTED WITHIN THE BOARD AREA, EXCEPT THOSE INDICATED IN THE DRILL LEGEND.
- PLATED HOLES - HOLES TO BE PLATED-THROUGH TO A FINISHED DIAMETER AS SHOWN IN DRILL LEGEND, MINIMUM THICKNESS .0014 UNLESS OTHERWISE SPECIFIED.
- SOLDER MASK - APPLY GREEN SOLDER MASK AS PER SPECIFIED IPC-SM-840 TO BOTH SIDES OF PCB OVER BARE COPPER
- SILKSCREEN - APPLY ON COMPONENT TOPSIDE OF PCB IN WHITE EPOXY BASED INK.



- CONFIDENTIAL -
 THIS DRAWING CONTAINS PROPRIETARY INFORMATION WHICH MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE WHATSOEVER OR USED FOR MANUFACTURING PURPOSES WITHOUT PRIOR WRITTEN PERMISSION FROM THE FUTURE ELECTRONICS CORPORATION.

 FUTURE ELECTRONICS	Future Electronics – Advanced Engineering Group 237 Hymus Blvd Pointe-Claire, Quebec, Canada H9R 5C7		
	Designed by: Navin Gautam	Project # PRJ-2858 – eHarvesting	
Drawn by: Navin Gautam	Title: Application DcDc 001		
Checked by: Hugo Letourneau	Size: A	DWG NO: FEN-2858-APDC001-PCB-R1	REV: 1
Approved by: Hugo Letourneau	Date: Jan 2 2012	Sheet 1 of 1	

Bill of Materials

Bill of Materials For Project [APDC_001_R01.PrjPCB] (No PCB Document Selected)

Source Data From APDC_001_R01.PrjPCB

Project: APDC_001_R01.PrjPCB

Variant: None

Created: 2012-02-15 14:10:54

Printed: 15-Feb-12 2:10:57 PM

Item#	Quantity	Designator	Value	Footprint	Description	MFR	MFR PN	Future PN (CT)	Future PN (TR)
1	2	C1, C2	22uF	1210[3225]	Cap Cer X5R 10V 20% 1210	TDK	C3225X5R1A226M	C3225X5R1A226M	C3225X5R1A226M
2	1	C3	100nF	0603(C1608)L	Cap Cer X7R 50V 10% 0603	TDK	C1608X7R1H104K	06035C104KATN-CT	06035C104KATN
3	1	L1	4.7uH	INDSMD7x7LS6.6	Inductor, Ferrite Core, 4.7uH, 4A (47mOhm)	Würth	744778004	NA	744778004
4	1	P1	18 Pin RA TH	HDR100-2X9-F-TH	Connector, Receptacle RA 2X9-Pin, LS100mil TH	Sullins	PPTC092LJBN-RC	PPTC092LJBN-RC	TBD
5	1	Q2	FDN340P	SOT23	Transistor Mosfet P-Chan -20V -2.0A (70 mOhm)	Fairchild	FDN340P	FDN340P	TBD
6	1	R1	560k	0603(R1608)L	Res 0603 100mW 1% 100ppm	Yageo	RC0603FR-07560KL	CR0603-5603FTR-CT	CR0603-5603FTR
7	1	R2	1M0	0603(R1608)L	Res 0603 100mW 1% 100ppm	Yageo	RC0603FR-071ML	CR0603-1004FTR-CT	CR0603-1004FTR
8	1	R3	330k	0603(R1608)L	Res 0603 100mW 1% 100ppm	Yageo	RC0603FR-07330KL	CR0603-3303FTR-CT	CR0603-3303FTR
9	1	R4	4k7	0603(R1608)L	Res 0603 100mW 1% 100ppm	YAGEO	RC0603FR-074K7L	CR0603-4701FTR-CT	CR0603-4701FTR-CT
10	1	R5	100k	0603(C1608)L	Res 0603 1/10W 5%	Yageo	RC0603JR-07100KL	CR0603-1003JTR-CT	CR0603-1003JTR
11	1	U1	AS1337A	TDFN-8-ETAB	IC, Regulator 200mA Step-up DC-DC 1.2MHz TDFN	Austriamicrosystems	AS1337A-BTDT	AS1337ATR-CT	AS1337ABTDT
12	1	U2		SOIC8	IC, 24AA024 Series 2 kb I2C Serial EEPROM	Microchip	24AA024-I/SN	24AA024WSOI	24AA024WSOI

Approved _____

Notes _____

--	--